GP2S22

Subminiature Photointerrupter

■ Features

1. ♦ 4mm compact resin mold type

2. Focal distanse: 0.6mm

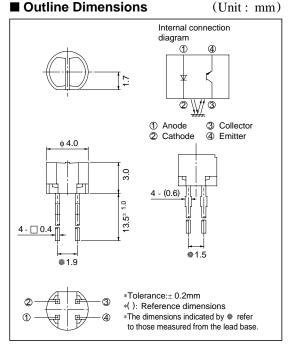
3. Visible light cut-off type

■ Applications

1. Audio equipment

2. VCRs

■ Outline Dimensions



■ Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

			`		
	Parameter	Symbol	Rating	Unit	
	Forward current	I_{F}	50	mA	
Input	Reverse voltage	V _R	6	V	
	Power dissipation	P	75	mW	
	Collector-emitter voltage	V _{CEO}	35	V	
Output	Emitter-collector voltage	V _{ECO}	6	V	
	Collector current	Ic	20	mA	
	Collector power dissipation	P _C	75	mW	
	Total power dissipation	P _{tot}	100	mW	
	Operating temperature	T opr	- 25 to + 85	°C	
	Storage temperature	T stg	- 40 to + 100	°C	
	*1Soldering temperature	T _{sol}	260	°C	

²mm or more Soldering area

^{*1} For 3 seconds by manual soldering

■ Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage		$V_{\rm F}$	$I_F = 20 \text{mA}$	-	1.2	1.4	V
	Reverse current		I_R	$V_R = 6V$	-	-	10	μΑ
Output	Collector dark current		ICEO	$V_{CE} = 20V$, $I_F = 0$	-	10 -9	10-7	Α
Transfer characteristics	*2Collector current		Ic	$V_{CE} = 2V$, $I_F = 4mA$	20	-	125	μΑ
	Response time	Rise time	t _r	$V_{CE} = 2V, I_{C} = 100 \mu A$	-	20	100	μs
		Fall time	tf	$R_L = 1k\Omega$, $d = 1mm$	-	20	100	μs
	*3Leak current		ILEAK	$V_{CE} = 2V$, $I_F = 4mA$	-	-	0.1	μΑ

^{*2} The condition and arrangement of the reflective object are shown in the following drawing.

The ranking of collector current shall be classified into the following 6 ranks.

Rank	I _C (μ A)		
A	58 to 125		
В	34 to 71		
С	20 to 42		
A or B	34 to 125		
B or C	20 to 71		
A, B or C	20 to 125		

Test Condition and Arrangement for Collector Current

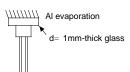


Fig. 1 Forward Current vs.

Ambient Temperature

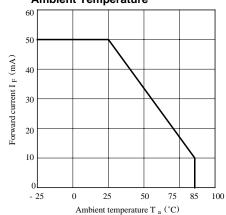
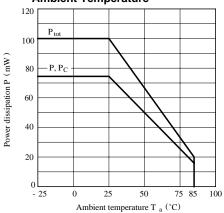


Fig. 2 Power Dissipation vs.
Ambient Temperature



^{*3} Without reflective object

Fig.3 Forward Current vs. Forward Voltage

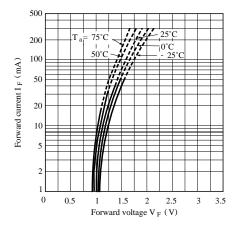


Fig. 5 Collector Current vs.
Collector-emitter Voltage

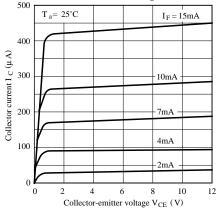


Fig. 7 Collector Dark Current vs.
Ambient Temperature

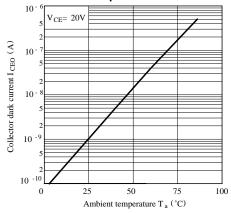


Fig.4 Collector Current vs. Forward Current

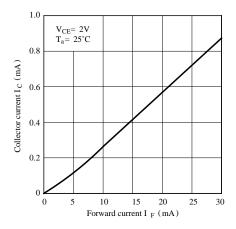


Fig. 6 Collector Current vs.

Ambient Temperature

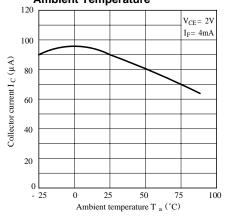
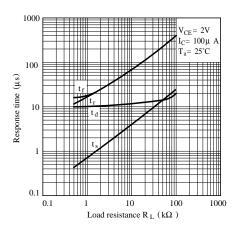


Fig. 8 Response Time vs. Load Resistance



Test Circuit for Response Time

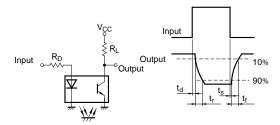


Fig.10 Relative Collector Current vs. Card Moving Distance

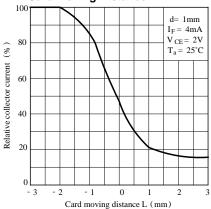
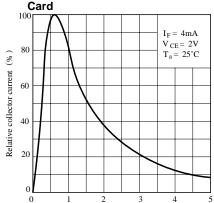
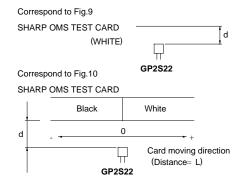


Fig. 9 Relative Collector Current vs.
Distance between GP2S22 and



Distance between GP2S22 and test card d (mm)

Distance Characteristics Test Condition



■ Precautions for Use

- (1) Perform soldering manually
- (2) Please refrain from soldering under preheating and refrain from soldering by reflow.
- (3) As for other general cautions, refer to the chapter "Precautions for Use".

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